



Inseto News Release – December 2007

**"Advanced Dicing Technologies (ADT) Appoint
Inseto As Their New UK & Irish Distributor"**

Prologue:

- **Advanced Dicing Technologies (ADT) a world leader in the manufacture of dicing saws, laser scribing systems and dicing blades has appointed Inseto as their new UK and Irish distributor.**
- **ADT's dicing equipment and blades are used to cut and scribe silicon wafers, ceramics, glass, sapphire, quartz and other hard materials, including package based devices such as BGA's and QFN's.**
- **Inseto provides advanced manufacturing equipment and related consumable products for electronic production, including Semiconductor, PCB & Microelectronic Assembly.**

-----End Prologue-----

Image: ADT 7100 Series Semiautomatic Dicing Saws
Download Version Available From: <http://www.inseto.co.uk/news/news.shtml>)



News Release:

Advanced Dicing Technologies (ADT) a world leader in the manufacture and development of dicing equipment and annular dicing blades has appointed Inseto as their new UK and Irish distributor.

ADT's extensive range of products includes semi and fully automatic dicing equipment, laser scribing equipment for removing low K materials prior to dicing, wafer mounting, post dice cleaning systems, UV tape curing equipment and annular (hubless) dicing blades.

The dicing saws are available in versions suitable for up to 300mm (12") wafers, with either 50mm (2") air bearing spindles for dicing wafers, thin materials and packages, or with high power 4" air bearing spindles for dicing thick and hard materials including glass, sapphire, quartz & ceramics. An elegant graphical user interface simplifies programming and incorporates full vision alignment, automatic kerf-check, blade-wear forecasting, and multi-panel dicing for increased productivity.

The dicing blade division of ADT, which has been producing blades for over 30 years, manufactures Resin-bond blades that are cured under pressure and high temperature and are used for dicing hard materials, Metal-bond sintered blades used for applications with an intermediate hardness including Soft Alumina, TiC, LTCC and Ferrite, and Nickel-bonded blades that are manufactured using a tightly controlled electroforming process and are suitable for dicing soft materials such as silicon & BGA's.

-----End News Release-----

Further information on Inseto & ADT can be found on our respective websites:

www.inseto.co.uk
www.adt-dicing.com

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